

06-26-1998

ASSIG



OVER SHEET

100748542

JCL35 U.S. PTO
09/098445
06/17/98

To: Honorable Commissioner of Patents and Trademarks:

Please record the attached original document(s) or copy thereof.

1. Name of conveying party(ies)
a) Inderjit Singh
b) Seshadri Vikram
2. Name and address of receiving party(ies):
a) Name: National Semiconductor Corporation
Address: 2900 Semiconductor Drive
Santa Clara, CA 95052
3. Nature of conveyance
☒ Assignment
☐ Security Agreement
☐ Other _____
☐ Merger
☐ Change of Name
☐ License Agreement
- mer
6-17-98*

Execution Date: June 17, 1998

4. Application Number(s) or Patent Number(s): Unknown

The title of the (new) application is:

09 098445

**WIRE BONDING APPARATUS FOR HEAT SENSITIVE METALLIZATION
USING A FLOATING PEDESTAL**

5. Please send all correspondence concerning this (these) documents to:

Steve D Beyer
BEYER & WEAVER, LLP
P.O. Box 61059
Palo Alto, CA 94306
Tel. No.: (650) 493-2100
Fax No.: (650) 493-2102

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$40.00

- ☒ Enclosed
☒ Any deficiencies are authorized to be charged to Deposit Account No.
50-0388 (Order No. NSCIP112)

8. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Date: June 17, 1998

SD Beyer

Steve D Beyer
Registration No. 31,234

06/23/1998 BHINES 00000094 09098445

03 FC:581

40.00 OP

Attorney Docket No. NSCIP112

PATENT (Revised 01/96)

REEL: 9258 FRAME: 0498

ASSIGNMENT OF PATENT APPLICATION

(Accompanying Application)

Whereas I/we the undersigned inventor(s) have invented certain new and useful improvements as set for in the patent application entitled:

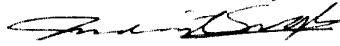
WIRE BONDING APPARATUS FOR HEAT SENSITIVE METALLIZATION USING A FLOATING PEDESTAL

(Atty. Docket No.: NSC1P112) for which I (we) have executed an application for a United States Letters Patent.

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I/We the undersigned inventor(s) hereby:

- 1) Sell(s), assign(s) and transfer(s) to **National Semiconductor Corporation**, a California corporation having a place of business at 2900 Semiconductor Drive, Santa Clara, California, (hereinafter referred to as "ASSIGNEE"), the entire right title and interest in any and all improvements and inventions disclosed in, application(s) based upon, and Patent(s) (including foreign patents) granted upon the information which is disclosed in the above referenced application.
- 2) Authorize and request the Commissioner of Patents to issue any and all Letters Patents resulting from said application or any division(s), continuation(s), substitutes(s) or reissue(s) thereof to the ASSIGNEE.
- 3) Agree to execute all papers and documents and, entirely at the ASSIGNEE's expense, perform any acts which are reasonably necessary in connection with the prosecution of said application, as well as any derivative and applications thereof, foreign applications based thereon, and/or the enforcement of patents resulting from such applications.
- 4) Agree that the terms, covenants and conditions of this assignment shall inure to the benefit of the Assignee, its successors, assigns and other legal representative, and shall be binding upon the inventor(s), as well as the inventor's heirs, legal representatives and assigns.
- 5) Warrant and represent that I/we have not entered, and will not enter into any assignment, contract, or understanding that conflicts with this assignment.

Signed on the date(s) indicated beside my (our) signature(s).

1) Signature:  Date: 6/17/98
Typed Name: Inderjit Singh

On this ____ day of _____, in the year 1998, before me, _____, personally appeared Inderjit Singh, personally known to me (or proved to me on the basis of satisfactory evidence) to be the person whose name is subscribed to the within instrument, and acknowledged to me that he/she executed the same in his/her authorized capacity(ies), and that by his/her signature on the instrument the person, or the entity upon behalf of which the person acted, executed the instrument.

WITNESS my hand and official seal.

Signature _____

(SEAL)

2)

Signature: _____

Typed Name: Seshadri Vikram

Date: 06/17/98

On this _____ day of _____, in the year 1998, before me, _____, personally appeared Seshadri Vikram, personally known to me (or proved to me on the basis of satisfactory evidence) to be the person whose name is subscribed to the within instrument, and acknowledged to me that he/she executed the same in his/her authorized capacity(ies), and that by his/her signature on the instrument the person, or the entity upon behalf of which the person acted, executed the instrument.

WITNESS my hand and official seal.

Signature _____
(SEAL)